ABSOCIATION CONNECTING ELECTRONICE INDUSTRIES INDUSTRIES INDUSTRIES	ckburn, Illinois. A	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declara he declaration	tion of the s	substances es all lowe	within the manufactu er level materials for w	rer listed i which the r	item. Note: nanufacture	if the item is an as r has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg Information			
Supplier Information													
mpany name* Company unique ID				Unique ID Authority					Response Date*				
onsemi	emi								2025-06-08				
Contact Name	Title - Contact				Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards	vards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
norized Representative* Title - Representative				Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product Enviro Compliance					NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr I	em Number	Mfr Item Name			Effective Da	e Version	L	Manufacturing Site		Weight*	UOM	Unit Type	
MME	TA64LT1G	A64LT1G SS SOT23 DL XS			2025-06-08			CN1		8.02	mg	Each	
Manufacturing Proccess Information		·			•							·	
Terminal Plating / Grid Array Material	Terminal Base Alloy		-STD-020 MSL	Rating	Peak Pro	ocess Body Temperature Max Time at Peal		Temperature Number of Reflow Cycles		les			
Matte Tin (Sn) - annealed CU Alloy 1			l		260		С	30	secoi	nds 3			
Comments													
level 1 - maximum time at peak temperature during	soldering is 10-3	0 seconds											
For more information regarding material compositi	on please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.05	mg	Supplier	Silicon (Si)	7440-21-3		0.05	mg
Lead Frame	2.92	mg	В	Nickel (Ni)	7440-02-0		1.06	mg
			Supplier	Iron (Fe)	7439-89-6		1.4658	mg
			Supplier	Copper (Cu)	7440-50-8		0.3942	mg
Mold Compound-Black	4.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.49	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0245	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7105	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.185	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.49	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond	0.01	mg	Supplier	Palladium (Pd)	7440-05-3		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0099	mg